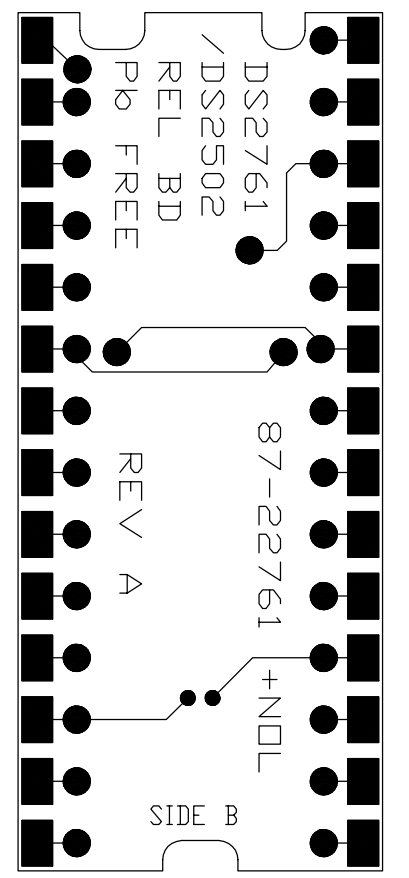
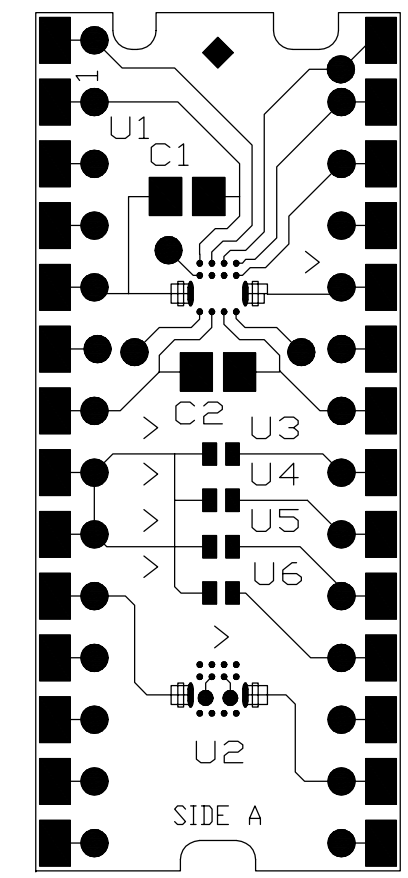


- NOTES:
- THE FOLLOWING ABIDES BY THE DSC INSPECTION DOCUMENTATION: # 27-00200-000.
  - PART MUST WITHSTAND, WITH NO BLISTERING, DELAMINATION, SOLDERMASK FLAKING OR ANY OTHER DAMAGE 3 REFLOW PASSES WITH MAXIMUM TEMPERATURE OF 260± 5° C AND 45 TO 90 SECONDS ABOVE 200° C FOLLOWED BY AQUEOUS OR SEMIAQUEOUS CLEANING.
  - A) MINIMUM DESIGNED CONDUCTOR WIDTH IS 0.005.  
B) MINIMUM DESIGNED CONDUCTOR SPACE IS 0.005.  
C) MAXIMUM ALLOWABLE LINE REDUCTION DUE TO PIN HOLES, NICKS ON LINE RUNS, AND LINE SHRINKAGE TO BE 10%.
  - MINIMUM LAYER TO LAYER DIELECTRIC FINISH .003, FOR MULTILAYER BOARDS ONLY.
  - COPPER WALL THICKNESS TO MEET IPC-600 CLASS 2.
  - MINIMUM ANNULAR RING PER IPC-6012A (CURRENT REVISION) CLASS 2.
  - ALL FIDUCIAL ALIGNMENT MARKS ARE TO BE PLATED PER THE PROCESS BELOW. MAXIMUM 10% SIZE REDUCTION ALLOWED, .250 SOLDERMASK CLEARANCE AROUND FIDUCIALS.
  - SOLDERMASK ; MASK HEIGHT MUST NOT EXCEED .0014 INCHES.
  - SOLDERMASK REGISTRATION TO BE ± .003.
  - SIDE TO SIDE REGISTRATION TO BE ± .003.
  - REMOVE ALL BURRS AND SHARP EDGES IN ORDER TO MEET DIMENSIONAL TOLERANCES.
  - THE FOLLOWING MUST BE PRESENT & LOCATED PER PAGE 2. (ETCHED, SOLDERMASK, SILKSCREENED OR STAMPED WITH NON-CONDUCTIVE INK).  
A) "PART NUMBER"  
B) "REVISION LETTER"  
C) "SIDE A" FOR SIDE A, "SIDE B" FOR SIDE B.  
D) DATE CODE  
E) MANUFACTURER'S UL LOGO
  - EXTERNAL COPPER WEIGHT WILL NOT EXCEED 1.5 OZ.
  - MAXIMUM ALLOWABLE WARP PER IPC-600.
  - SOLDERMASK ARTWORK MUST NOT BE EDITED IN ANY WAY. THE ARTWORK MANDATES A MINIMUM CLEARANCE AROUND BOARD EDGE TO REDUCE PEELING AND KEEP MASK OFF EDGE CONNECTORS AND LEAD FRAME PADS IF APPLICABLE.

NO.	DESCRIPTION	STARTING COPPER WT.	REVISION
1.	SIDE A SOLDERMASK		A
2.	LAYER 1 SURFACE (SIDE A)	0.5 OZ.	A
3.	LAYER 2 SURFACE (SIDE B)	0.5 OZ.	A
4.	SIDE B SOLDERMASK		A

DESCRIPTION	SIDE	REVISION
HOLE CONFIGURATION	A	A
HOLE CONFIGURATION	B	
CONTINUITY TEST	A	
CONTINUITY TEST	B	
PROFILE	A	
PROFILE	B	



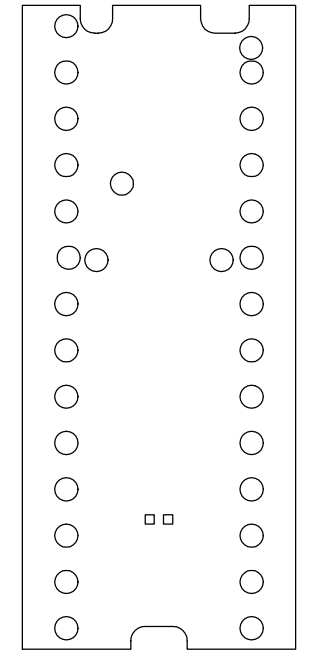
SIDE - A

SIDE - B

( FOR REFERENCE ONLY NOT TO SCALE )

- PROCESSES: SOLDERMASK OVER BARE COPPER (SMOBC) AND ELECTROLESS Ni IMMERSION GOLD (ENIG). MUST MEET IPC-S-804 SOLDERABILITY.
- Au (IMMERSION 3-10 MICRO INCHES).
  - Ni (ELECTROLESS 100-300 MICRO INCHES).
  - SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.

- PROCESSES: ELECTROLYTIC Ni GOLD MUST MEET IPC-S-804 SOLDERABILITY.
- Au (ELECTROLYTIC 10-30 MICRO INCHES).
  - Ni (ELECTROLYTIC 100-500 MICRO INCHES).
  - SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.



( FOR REFERENCE ONLY NOT TO SCALE )  
( SIDE A SHOWN )

X = CRITICAL DIMENSION					
HOLE SCHEDULE					
SYM	FINISHED HOLE DIAMETER		HOLE COUNT		REMARKS
	UNSUPPORTED	PLATED THRU +.007-.003	CELL	PANEL	
⊕	.120 ±.003			4	PANEL TOOLING HOLES
□		.012	2	48	PCB VIA (TENTED)
○		.020	31	744	PCB VIA

REF	DESCRIPTION	QTY REQD	QTY REQD	QTY REQD	QTY REQD	QTY REQD	ITEM NO.	MFG FSCM	PART NUMBER OR IDENTIFYING NO.	NOMENCLATURE OR DESCRIPTION
5.	MP****									MASTER PATTERN
4.	PREPREG									BONDING LAYER, TYPE GF OF MIL-P-13949, IF REQUIRED
3.	SOLDERMASK									SOLDERMASK, TYPE B1: COLOR GREEN
2.	(NOTE 2) FLGFN C1/0 A3B									LAMINATE-MULTIFUNCTIONAL, FR4, TYPE GF, UL APPROVED, WITH A tg>170° CELSIUS PER IPC-4101, SPECIFICATION SHEET #24 INTERNAL LAYER OR SIMILAR MATERIAL
1.	(NOTE 2) FLGFN C.5/.5 A3B									LAMINATE-MULTIFUNCTIONAL, FR4, TYPE GF, UL APPROVED, WITH A tg>170° CELSIUS PER IPC-4101, SPECIFICATION SHEET #24 TOP LAYER OR SIMILAR MATERIAL

UNLESS OTHERWISE SPECIFIED	SIGNATURE	DATE	SIGNATURE	DATE
PCB DESIGNER: T.BASS	T.BASS	11/02/04	ASSY ENGR: GUY RUPP	11/02/04
TEST ENGR: TIM BENNETT	TIM BENNETT	11/02/04	BUY PROD ENGR: G.ARMSTRONG	11/02/04
QA APVD: R.SHINE	R.SHINE	11/02/04	DES ENGR: J. SMITH	11/02/04
DOC CONTROL: J.WALKER	J.WALKER	11/02/04	CHECK BY: C.A.D.	11/02/04
SMT ASSY ENGR: T.TSUI	T.TSUI	11/02/04	DRAWN BY: T.BASS	11/02/04

**DALLAS SEMICONDUCTOR MAXIM**

PCB, DS2761/DS2502 REL. BD., Pb FREE

SIZE D	FSCM NO	DWG NO 87-22761+NOL	REV A
SCALE N/A	PROJECT 735	SHEET 1 OF 2	

